

pro-bond 9F VT-468 RCF

UL Approval: E214381 Version: 30/10/2025

Extremely Low Dk/Df prepreg & Resin Coated Film Bondply

VT-468 RCF is non-reinforced film type material, which eliminates the skew and variation in high speed digital application with extremely low loss property (Df 0.0005@10GHz). It is designed to bond all circuit board materials and is more friendly to PCB process because of the thermosetting resin system.

General Information

- > Excellent rheology properties for filling circuits
- > Excellent through hole reliability
- > Non-glass fabric reinforced, excellent electrical isotropic consistency
- > Stable Dk over temperature
- > Friendly for laser drill process
- > Suitable for sequential laminations
- > Halogen free

Application

- > Data center
- > HPC
- > Radar and antenna

Availability

- > 50µm, 100µm, 125µm, and other thickness option could be available based upon request.

Storage Condition

Properties		RCF	
Storage Condition	Temperature	Below 23°C (73°F)	Below 5°C (41°F)
	Relative humidity	Below 55% RH	/

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Properties Sheet

Item		Test Method	Units	Typical Value
Dk@10GHz		IPC-TM-650 2.5.5.13	-	2.80
Df@10GHz		IPC-TM-650 2.5.5.13	-	0.0005
Tg-DMA		IPC-TM-650 2.4.24.4	°C	205
T288		IPC-TM-650 2.4.24	min	>60
Td(5% WT. loss)		ASTM D3850	°C	440
Peel strength	1oz HTE	IPC-TM-650 2.4.8	Lb/in	5.0
	1oz RTF			4.5
	1oz HVLP			4.0
X/Y-CTE (50~130°C)		IPC-TM-650 2.4.41	ppm/°C	35
Z-CTE (50~130°C)		IPC-TM-650 2.4.24	ppm/°C	35
Z-CTE (50~260°C)		IPC-TM-650 2.4.24	%	1.3%
Thermal conductivity		ASTM D5470	W/mK	0.6
Moisture absorption		IPC-TM-650 2.6.2.1	%	0.08
Flammability		UL 94	°C	V-0

All test data provided are typical values and not intended to be specification values.

Disclaimer: The information and data contained in this technical literature is based on data and knowledge correct at the time of publishing/printing and is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.